ABSTRACT OF THE DISCLOSURE

In a method of coating a semiconductor wafer with a resin of the present invention, first, a semiconductor wafer (4) is placed on a bottom surface of a cavity (5) provided in a molding surface of a lower mold of a mold with its surface having a bump facing upward. Thereafter, a required amount of resin material (6) is supplied to cavity (5), and a film (7) for exposing the bump is applied to a molding surface of the upper one of the molds (1, 2). In this state, molds (1, 2) are closed together. Resin material (6) is heated to melt in cavity (5). Then, film (7) is pressed against the bottom surface of cavity (5) by a pressing member (8) provided on the molding surface of the upper mold, so that film (7) is abutted against a leading edge of bump (3) in cavity (5). A pressure is applied to the resin in cavity (5) through film (7), and the surface having the bump of semiconductor wafer (4) is coated with resin. According to the method, pressing member (8) is provided on the upper mold, so that melted resin does not enter a sliding portion. Accordingly, productivity of the resin-coated wafer increases and a resin-coated wafer with high quality and reliability is obtained.

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